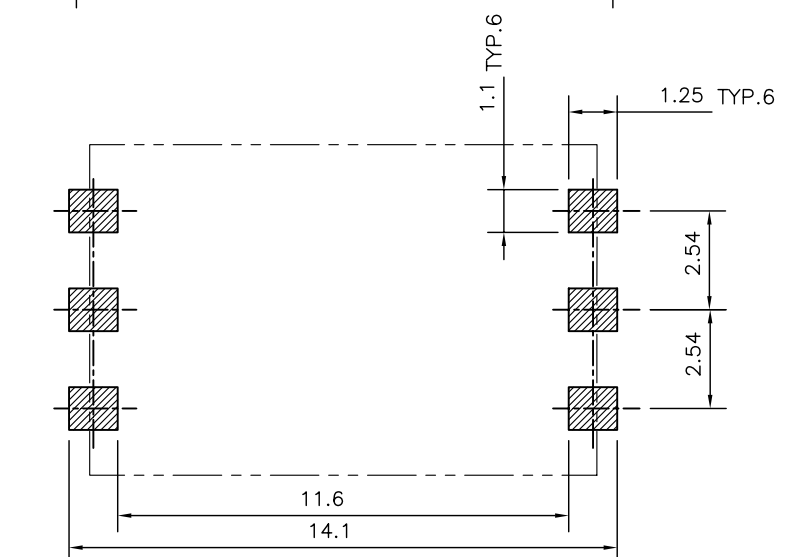
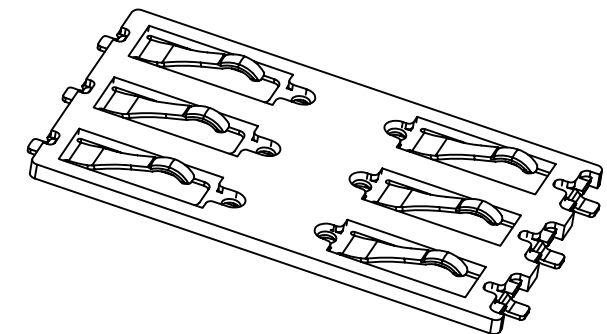
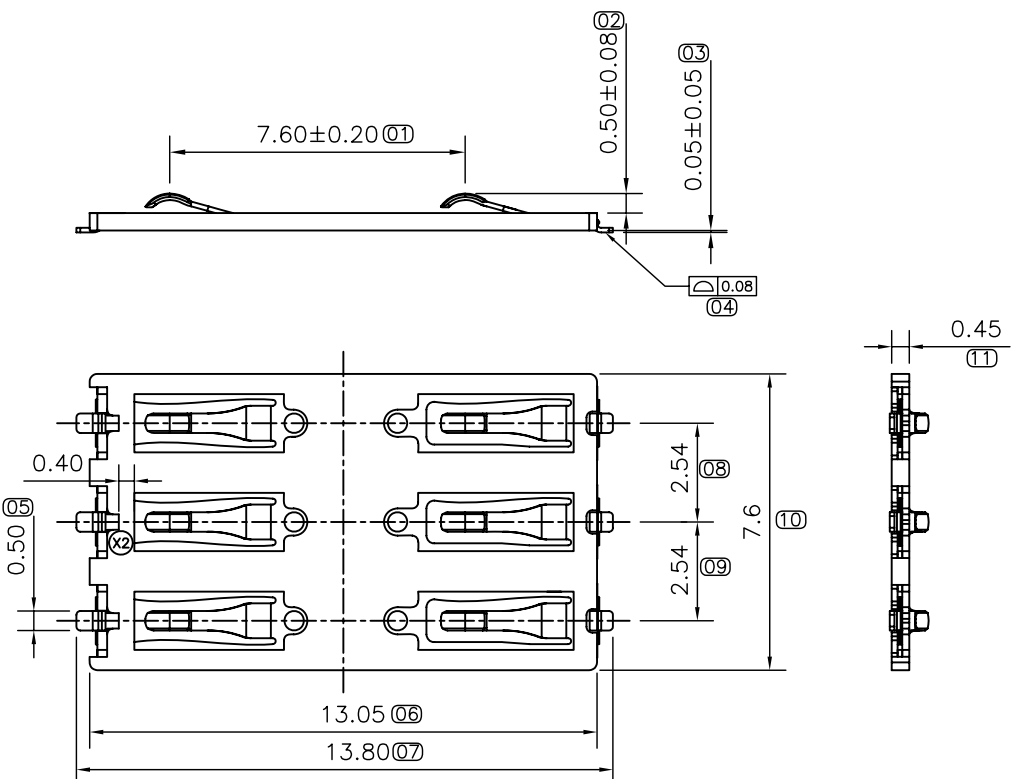


REV	ECN NO	DESCRIPTION	DATE	APPD
x1		BRAN-NEW	2008.04.12	HANSEN
X2	PECN1309011	塑件加胶0.15mm	2013.09.29	TLH



RECOMMENDED PCB LAYOUT
(TOLERANCE +/-0.05)

NOTE:

- 1: HOUSING MATERIAL: THERMAL PLASTIC, COLOR: BLACK;
- 2: CONTACT MATERIAL: COPPER ALLOY;
- 3: PLATING:
15u"(0.375um)Min. GOLD PLATING ON CONTACT AREA;
100u"(2.54um)Min. MATTE-TIN PLATING ON SOLDER AREA.
- 4: PERFORMANCE:
 - 4.1: CONTACT RESISTANCE: 60mOHM Max.
 - 4.2: DIELECTRIC WITHSTANDING VOLTAGE: 200 VAC FOR 1MINUTE;
 - 4.3: INSULATION RESISTANCE: 1000MOHM Min.
 - 4.4: DURABILITY: 5000 TIMES Min.

EXTEND USE		TITLE		FAP.	
MICRO SIM CARD 0.5H		MICRO SIM CARD 0.5H		C-1.038A0	
UNIT mm		ASSEMBLY DRAWING		DWG NO	
GENERAL TOLERANCE (11)		MATERIAL APPD 谭林红 2013.09.29		P/N:	
DIMENSION		QTY CHD 谭林红 2013.09.29		1.038A0-006-5R0	
ANGLES		FINISHED DRN 黄文珠 2013.09.29		SHEET SCALE (11) REV X2	
. ±0.30	. ±3'			1/1 1:1	
.0 ±0.25	.0 ±2'				
.00 ±0.20	.00 ±1'				
.000 ±0.10					